Europe System in Package (SiP) Technology Market (2016-2022)

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Abstracts

The Europe System in Package (SiP) Technology Market is expected to grow at a CAGR of 12.6% during 2016 -2022.

The Europe system in package (SiP) technology market would witness significant growth during the forecast period 2016-2022, due to growing demand for portable electronic devices and growing popularity of Internet of Things (IoT). Printed circuit board (PCB) based ICs were mostly used in industrial systems for data transmission. However, other industries such as consumer electronics, energy & power, inverter & UPS, and automotive, have shifted to SiP to efficiently manage data transfer. The Sip technology is an advanced technology and as the levels of awareness increase, the demand for SiP would significantly grow.

To enhance the efficiency levels, market players are developing innovative products for applications in telecommunication and electronic appliances. The use of SiP enables high frequency data transfer to improve efficiency and prevent power loss. Low power consumption and a highly competitive market have forced industries to adopt 2.5D IC packaging technology, stimulating the growth of the SiP market.

The report highlights the adoption of System in Package (SiP) Technology in Europe. Based on the Type, the Europe System in Package (SiP) Technology market is segmented into 2-D IC Packaging, 2.5-D IC Packaging and 3-D IC Packaging segments. Based on the Packaging Type, the market is bifurcated into Flat Packages, Pin Grid Arrays, Surface Mount, Small Outline Packages and Other Packaging segments. The Europe System in Package (SiP) Technology market is further segmented into Wire Bond, Flip Chip segments based on the Interconnection Technology. Further, the market is segmented into Consumer Electronics, Automotive,

Telecommunication, Industrial System, Aerospace & Defense and Other segments based on the various applications. The countries included in the report are Germany, UK, France, Russia, Spain, Italy and Rest of Europe.

Key Players profiled in the report includes Amkor Technology Inc., Jiangsu Changjiang Electronics Technology Co. Ltd., Chipmos Technologies Inc., Powertech Technology Inc., Ase Group, Renesas Electronics Corporation, Samsung Electronics Co. Ltd. and Toshiba Corporation.

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